

General Description:

JX-H63P is an HD CMOS image sensor designed with a superior 2.8µm pixel with excellent low-light sensitivity and low dark current performance. It features a 60fps native high definition (HD) 720p video capability for camera applications in PC multimedia, security, and entertainment devices.

The JX-H63P consists of a 1288x728 active pixel sensor (APS) array with an on-chip 10-bit ADC, programmable gain control (PGA), and correlated double sampling (CDS) to significantly reduce fixed pattern noise (FPN). The sensor also has many standard programmable and automatic functions. It has both the industry compliant DVP parallel and MIPI CSI2 serial interfaces. The external host controller can access this device through a standard serial interface.

It is available in wafer-level packaged CSP.

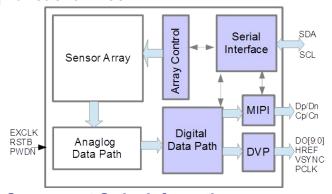
Features:

- · Automatic functions:
 - o ABLC Automatic Black Level Calibration
- Programmable controls:
 - o Gain, exposure, frame rate and size
 - o Image mirror and flip
 - o Window panning and cropping
 - o I2C slave ID
- · Output formats:
 - o DVP parallel interface
 - o MIPI CSI2 (1 lane)
- Data formats:
 - o 10-bit RAW RGB
- Others
 - o 50/60Hz flick noise cancellation
 - o Frame sync
 - o Register group write capability
 - o Black sun spot cancellation

Key Specifications:

Optical format		1/4"		
Active Pixels		1288H x 728V		
Pixel size		2.8 x 2.8 μm		
Color filter array		RGB Bayer pattern		
Chief Ray Angle		17.5 degrees linear		
Shutter type		Electronic rolling shutter		
Maximum Frame Rate		1280x720: 60fps HDR 1280x720: 30fps, 2 frames staggered output		
Supply voltage	Analog	2.6 - 3.0V (2.8V nominal)		
	I/O	1.7 – 3.0V (1.8V nominal)		
Power	Active	62 mW (DVP 30fps)		
consumption	Standby	Typ.: 300 uA		
Output Formats		10-bit RGB Raw Data		
Sensitivity		2900 mV/lux-sec		
Max SNR		41.0 db		
Dynamic range		84.9 db		
Dark Current		6.5 mV/sec @ 45 °C		
Operating temper	erature	-30 °C to 85 °C		
Stable image junction temper	ature	60 °C		

Functional Block:



Component Order Information:

Part Number	Description
JX-H63P-C1-D3	CSP, DVP @30fps
JX-H63P-C1-D6	CSP, DVP @60fps
JX-H63P-C1-M3	CSP, MIPI @30fps
JX-H63P-C1-M6	CSP, MIPI @60fps



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Pin Diagram:

JX-H63P's pin diagram is shown in Figure 1 and each pin's description is shown in Table 1:

Figure 1: JX-H63P CSP top view

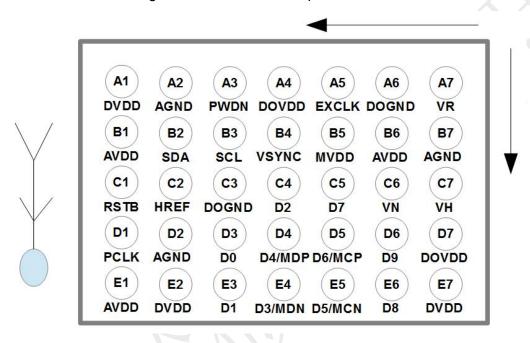




Table 1: Pin Description

Pin number	Pin name	Pin type	Description
A1	DVDD	Supply	Digital core supply voltage. With embedded regulator.
A2	AGND	Supply	Analog ground
A3	PWDN	Input	Chip power down initiate pin. High active.
A4	DOVDD	Supply	Digital I/O supply voltage.
A5	EXCLK	Input	System clock input.
A6	DOGND	Supply	Digital I/O ground
A7	VR	Reference	Internal analog reference.
B1	AVDD	Supply	Analog supply voltage.
B2	SDA	I/O	Serial data, pull to DOVDD with a 4.7k Ω resistor
B3	SCL	Input	Serial interface clock input.
B4	VSYNC	I/O	Vertical synchronize signal, drive high when last frame end and drive low before next frame start. Also can be programmed as frame synchronize input
B5	MVDD	Supply	MIPI block supply voltage, connect to DVDD pin.
B6	AVDD	Supply	Analog supply voltage.
B7	AGND	Supply	Analog ground
C1	RSTB	Input	System synchronize reset when driven low, it resumes normal operation with all configuration register set to factory default
C2	HREF	I/O	Line data valid signal output.
C3	DOGND	Supply	Digital I/O ground
C4	D2	I/O	DVP data output bit 2.
C5	D7	I/O	DVP data output bit 7.
C6	VN	Reference	Internal analog reference.
C7	VH	Reference	Internal analog reference.
D1	PCLK	I/O	Pixel clock.
D2	AGND	Supply	Analog ground
D3	D0/SID0	I/O	DVP data output bit 0; I2C Slave ID programming bit<0>, default pull down internally.
D4	D4/MDP	I/O	DVP data output bit 4 or MIPI data lane positive output.
D5	D6/MCP	I/O	DVP data output bit 6 or MIPI clock lane positive output.
D6	D9	I/O	DVP data output bit 9;
D7	DOVDD	Supply	Digital I/O supply voltage.
E1	AVDD	Supply	Analog supply voltage.
E2	DVDD	Supply	Digital core supply voltage. With embedded regulator.
E3	D1/SID1	I/O	DVP data output bit 1; I2C Slave ID programming bit<1>, default pull down internally. I2C slave ID can be programmed as "80/81", "84/85", "88/89" or "8C/8D" for write and read.
E4	D3/MDN	I/O	DVP data output bit 3 or MIPI data lane negative output.
E5	D5/MCN	I/O	DVP data output bit 5 or MIPI clock lane negative output.
E6	D8	I/O	DVP data output bit 8.
E7	DVDD	Supply	Digital core supply voltage. With embedded regulator.



Symbol **Equivalent Circuit** PAD **EXCLK** GND_DO EN · PAD **SDA** Open drain drive GND_DO PAD | SCL GND_DO | VDD DO Pull up \{ **RSTB** PAD GND_DO PAD **PWDN** GND_DO VDD_DO D9,D8,D7,D6,D5, D4,D3,D2,HREF,VS, PAD **PCLK** GND_DO VDD DO D1,D0 PAD GND_DO |

Table2: I/O Equivalent Circuit Diagram



MDP,MDN,MCP, MCN,VH,VR	GND_DO
VN	GND_DO PAD



Functional Overview:

The JX-H63P is a progressive-scan CMOS image sensor. It has an on-chip, phase-locked loop (PLL) to generate internal clocks from a single master input clock running between 6 and 27MHz. Figure 2 illustrates the sensor's block diagram.

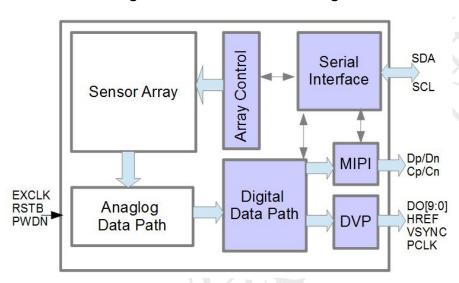


Figure 2. Functional Block Diagram

User can access and program JX-H63P sensor internal registers through the two-wire serial bus. The core of the sensor is a 1280x720 pixel array. The timing and control circuitry sequences through the rows of the array, resetting and then reading each row in turn. In the time interval between resetting and reading that row, the pixels in the row integrate the incident light. The exposure is controlled by varying the time interval between reset and readout. Once a row has been read, the data from the columns is sequenced through an analog signal path to apply gain and analog signal to digital signal converter (ADC). The ADC output passes through a digital processing path for black level calibration. Then the data will output though a DVP port or MIPI CSI-2 standard interface.



Pixel Array Format:

The JX-H63P pixel array consists of a 1288-column by 752-row matrix of pixels addressed by column and row. The address (column 0, row 0) represents the upper-right corner of the entire array (please refer to Figure 3,4 for JX-H63P's Pixel array structure). The first 24 rows are optical black row for black level calibration. Outside of the 1280x720 active pixels, there are several boundary pixels:4 rows on top, 4 rows at the bottom, 4 columns on the right, and 4 columns on the left. Please note that only performance of the active image area is defined in the outgoing specifications, performance of dummy columns and rows are not guaranteed as same as the active image. The detailed pixel array arrangement and default read out direction is noted in the following two figures:

Active Image 1280x720

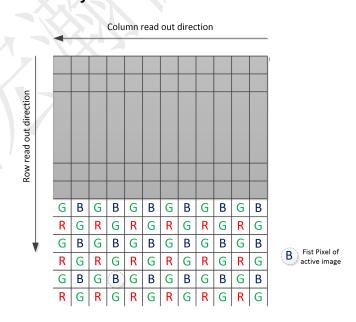
4 Dummy Row

Active Image 1280x720

4 Dummy Row

Figure 3: Pixel array structure

Figure 4: Pixel array detail with default read out direction.





Data Output Format:

The output images are divided into frames, which are further divided into lines. By default, the sensor produces 720 lines (rows) of 1280 columns each. The VSYNC and HREF signals indicate the boundaries between frames and lines, respectively. PCLK can be used as a clock to latch the data. For each PCLK cycle, one 10-bit pixel data outputs on the D[9:0] pins (Figure 5). The pixel data is valid when HREF signal is asserted. The VSYNC signal indicates frame end and new frame start. JX-H63P default frame timing is illustrated as figure 6.

Figure 5: Row data output timing

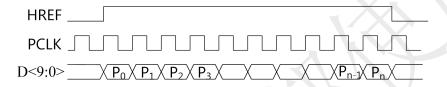
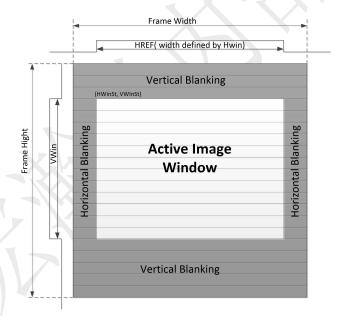


Figure 6: Default frame timing



As shown above in Figure 6, a line (row) period can be calculated as Trow = Frame_width * Thclk, and frame rate can be calculated as fps=1/(Frame_hight * Trow).

As default configuration, VSYNC, PCLK and Data are all valid at PCLK rising edge. For user convenience, JX-H63P provides register bits to control HREF, VSYNC and PCLK polarity. In addition, PCLK also have adjustable delay control.

For pixel Bayer pattern data output, several settings can have effect on pixel output sequences. These registers include HWIn_St, VWin St, Haddr St, Mirror, V Flip. Please consult your SOI AE for further information.

exposure longer than vertical blanking

Fram e_2_Short

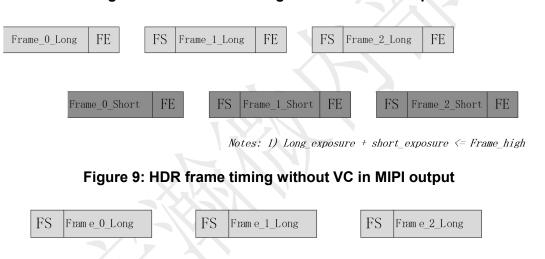
FE



HDR mode

JX-H63P support HDR mode, user can set 2 different exposure time and output 2 frame data (long and short exposure) in staggered output mode. Figure 7,8,9 are diagrams to illustrate frame output timing under this mode.

Figure 8: HDR frame timing with VC in MIPI output



Fram e_1_Short

Test Pattern Output:

JX-H63P can output following test patterns as described below:

Frame O Short

1) Walking "1" test pattern: for most sensor module connectivity test, JX-H63P provides walking "1" test pattern.



MIPI interface:

JX-H63P supports MIPI CSI-2 compliant interface. It has one pair of differential clock lane and one pairs of differential data lane. JX-H63P can output raw8 or raw10 mode through the MIPI interface. In raw8 mode, only 8 MSBs of 10-bit data will output and user needs to set MIPI clock speed at 8x parallel port pixel clock. In raw10 mode, user needs to set MIPI PHY clock as 10x parallel port pixel clock.

Figure 10: MIPI interface frame timing

Frame Synchronization:

JX-H63P provides the capability of frame synchronization. By setting VSYNC pin as input and enable frame-sync option, JX-H63P will work as slave device and synchronized with an external VSYNC. If all master devices and slave devices use same timing setting, all devices frame timing mismatch will be less than few pixel clocks. Figure 11 shows the ways to realize frame synchronization.

Ext.CLK

Figure 11: Frame Synchronization illustration



Serial Interface:

The serial interface is a two-wire bi-directional bus. Both wires (Serial Clock –SCL and Serial Data – SDA) are connected to DOVDD via a pull-up resistor, and when the bus is free both lines are high. The two-wire serial interface defines several different transmission stages as follows:

- · A start bit
- The slave device 7-bit address
- An (No) acknowledge bit coming from slave
- An 8-bit or 16-bit message (address and/or data)
- A stop bit (or another 8bit or 16bit message in multiple Read/Write access)

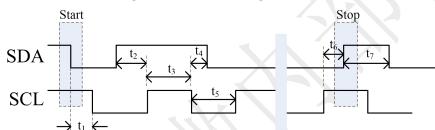


Figure 12: I2C Timing chart

Table 3: I2C timing characteristic

Symbol	Description	Min	Max	Units
	SCL clock frequency	0	400k	Hz
t1	Hold time for START condition	0.6	ı	μs
t2	Data setup time	160	-	ns
t3	High period of the SCL clock	0.6	-	μs
t4	Data hold time	0.2	0.9	μs
t5	Low period of the SCL clock	1.3	-	μs
t6	Setup time for STOP condition	0.6	-	μs
t7	Bus free time between STOP and	1.3	-	μs
	START condition			
	Rise time for both SDA and SCL signals		300	ns
	Fall time for both SDA and SCL signals		300	ns
Cb	Capacitive load for each bus line		400	pF



Single Write Mode operation



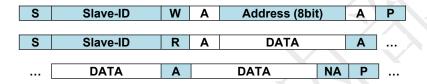
Multiple Write Mode (Register address is increased automatically) operation



Single Read Mode operation

S	Slave-ID	W	Α	Address (8bit)	Α	Р
S	Slave-ID	R	Α	DATA	NA	Р

Multiple Read Mode (Register address is increased automatically) operation



S: start conditions, A: acknowledge bit, NA: no acknowledge, DATA: 8 bit data, P: stop condition. JX-H63P slave ID is programmable, default is 0x80/81 for write and read. User can program DVP data bit<1:0> for other configuration. The slave ID program table is list below:

D[1]	D[0]	Read/Write
X	X	81/80
X	Pull high	85/84
Pull high	X	89/88
Pull high	Pull high	8D/8C

Register Writing:

In order to avoid register writing process for one frame being split into two frames by mistake, the register writing should be written as early as possible after VYSNC failing edge or MIPI frame start.

Register Group Write Function:

JX-H63P provides register group write function, user can pre-load address and data from register 0xC0 to 0xFF, then trigger this function by setting Reg0x1F[7], normally JX-H63P will auto write back group register content at next vertical sync period and reset Reg0x1F[7] JX-H63P can update up to 32bytes of registers.

User can monitor Reg0x1F[7] to make sure group write procedure is finished or not. The monitor I2C read process should not occurs at vertical sync period to prevent conflict with register group write process.



Power on/off sequence:

Figure 13 shows a reference power up sequence of JX-H63P.

Figure 13. Power up sequence for JX-H63P

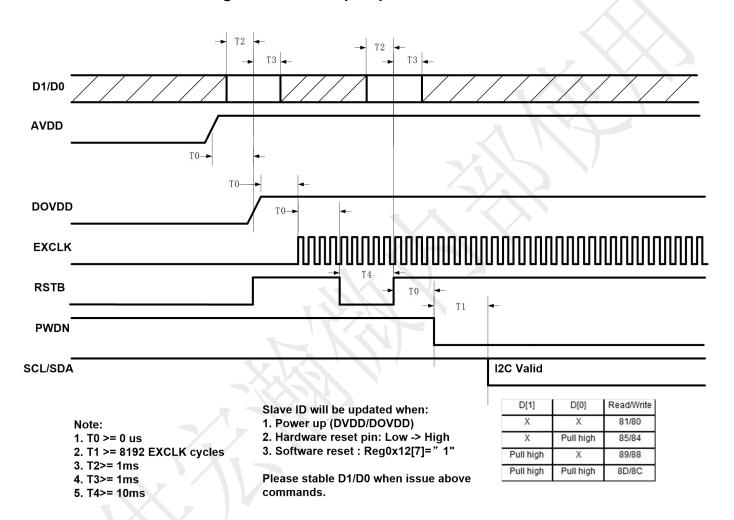
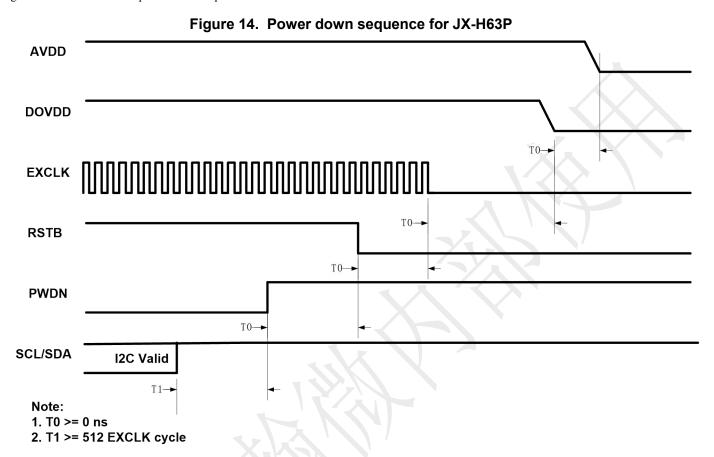




Figure 14 shows a reference power down sequence of JX-H63P.





Electrical Characteristics:

Table 4. Absolute maximum ratings

Symbol	Descriptions	Absolute maximum rating	Units
V _{DD-IO}	I/O Digital Power	4.5	V
V _{DD-A}	Analog Power	4.5	V
$V_{\text{DD-D}}$	Core Digital Power	3.0	V
Vı	Input voltages	-0.3v to V _{DD-IO} + 1V	V
T _{AS}	Ambient Storage Temperature	-40 ~ 125	°C

Table 5. DC Characteristics (0°C ≤ TA ≤ 85°C, Voltages referenced to GND)

	•				
Symbol	Descriptions	Max	Тур	Min	Units
supply					
$V_{\text{DD-IO}}$	Supply voltage (DOVDD)	3.0	1.8	1.7	V
$V_{\text{DD-A}}$	Supply voltage (AVDD)	3.0	2.8	2.6	V
Digital In	puts				
V_{IL}	Input voltage LOW	0.2* V _{DD-IO}	-	-	V
V_{IH}	Input voltage HIGH			$0.7*V_{DD-IO}$	V
C _{IN}	Input capacitor	10			pF
Digital O	utputs (loading 20pF)				
Vон	Output voltage HIGH			V _{DD-IO} – 0.2	V
V _{OL}	Output voltage LOW	0.2			V
Power co	nsumption (Internal DVDD, MVDD short to DVDD; DVP o	output mode; AV	DD=2.8V, [DOVDD=1.8V)	
I_{DD-IO}	Supply current		11		mA
	(V _{DD-IO} =1.8V@30fps HD without digital I/O loading)				
I_{DD-A}	Supply current		15		mA
	(V _{DD-A} =2.8V@30fps HD)				
Power co	nsumption (Internal DVDD, MVDD short to DVDD; MIPI o	output mode; AV	DD=2.8V, [DOVDD=1.8V)	
I_{DD-IO}	Supply current		17		mA
	(<u>V_{DD-IO}=1.8V@30fps</u> MIPI HD)				
I_{DD-A}	Supply current		15		mA
	(V _{DD-A} =2.8V@30fps MIPI HD)				
Ipwrdn	HW PWDN Pin active		300		uA



CRA Specifications:

JX-H63P is designed with a linear chief ray angle curve as shown in Figure 15. The shifting of the color filter and micro lenses on the sensor is critical to accommodate the ever-shorter height of the camera module as well as minimizing shading at the corner of the image.

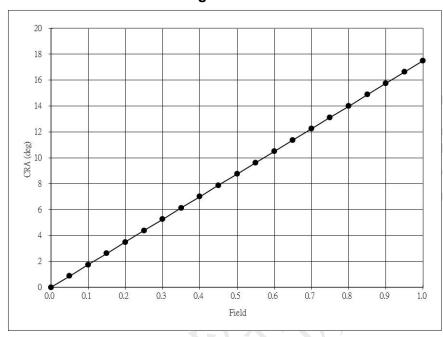


Figure 15. CRA Curve for JX-H63P

Field	CRA
0.00	0.000
0.05	0.875
0.10	1.750
0.15	2.625
0.20	3.500
0.25	4.375
0.30	5.250
0.35	6.125
0.40	7.000
0.45	7.875
0.50	8.750
0.55	9.625
0.60	10.500
0.65	11.375
0.70	12.250
0.75	13.125
0.80	14.000
0.85	14.875
0.90	15.750
0.95	16.625
1.00	17.500



Mechanical Specifications:

JX-H63P is available in CSP packaged component. Figure 16 shows top view and bottom view of the CSP component. Table 5 shows the nominal dimensions for the packaged chip. BGA Center = (-0.12um, 1.08um); Optical center = (13.0um, 116.0um).

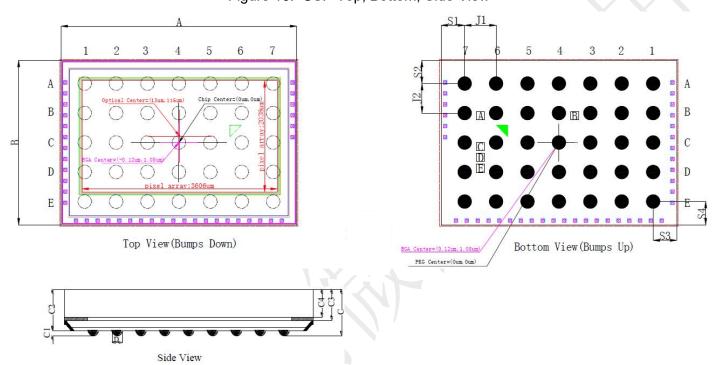


Figure 16. CSP Top, Bottom, Side View

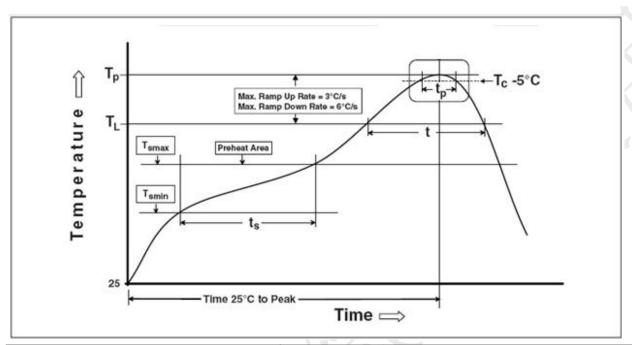
Table 6. Dimensions for JX-H63P CSP package (in mm)

	Symbol	Nominal	Min	Max	Nominal	Min	Max	
		Millimeters			-	Inches		
Package Body Dimension X	Α	4.350	4.325	4.375	0.17126	0.17028	0.17224	
Package Body Dimension Y	В	3.010	2.985	3.035	0.11850	0.11752	0.11949	
Package Height	С	0.670	0.610	0.730	0.02638	0.02402	0.02874	
Ball Height	C1	0.130	0.100	0.160	0.00512	0.00394	0.00630	
Package Body Thickness	C2	0.540	0.505	0.575	0.02126	0.01988	0.02264	
Thickness from top glass surface to wafer	C3	0.345	0.325	0.365	0.01358	0.01280	0.01437	
Glass Thickness	C4	0.300	0.285	0.315	0.01181	0.01122	0.01240	
Ball Diameter	D	0.250	0.220	0.280	0.00984	0.00866	0.01102	
Total Ball Count	N	35						
Pins pitch X axis	J1	0.580						
Pins pitch Y axis	J2	0.540					s,	
Edge to Pin Center Distance along X1	S1	0.43512	0.405120	0.465120	0.01713	0.01595	0.01831	
Edge to Pin Center Distance along Y1	S2	0.42392	0.393920	0.453920	0.01669	0.01551	0.01787	
Edge to Pin Center Distance along X1	S3	0.43488	0.404880	0.464880	0.01712	0.01594	0.01830	
Edge to Pin Center Distance along Y1	S4	0.42608	0.396080	0.456080	0.01677	0.01559	0.01796	



IR Reflow:

Recommended IR-reflow profile and condition



Profile Feature	Green Assembly
Preheat & Soak	
Temperature min (T _{Smin})	150°C
Temperature min (T _{Smax})	200°C
Time (T _{Smin} to T _{Smax}) (t _S)	90-150 seconds (Optimal 100)
Average ramp-up rate(Tsmax to T _P)	3°C/second max.
Liquidous temperature (T _L)	217°C
Time at liquidous (t₁)	60-150 seconds (Optimal 120)
Peak package body temperature (T _P)*	240 +/-5°C
Time (t_P) within 5°C of the specified classification temperature (T_C)	10~30 seconds
· ` ` ` ` ` ` ` ` ` ` ` ` ` ` ` ` ` ` `	26.
Average ramp-down rate (T _P to Tsmax)	6°C/second max.
Time 25°C to Peak temperature	8 minutes max.

Note:

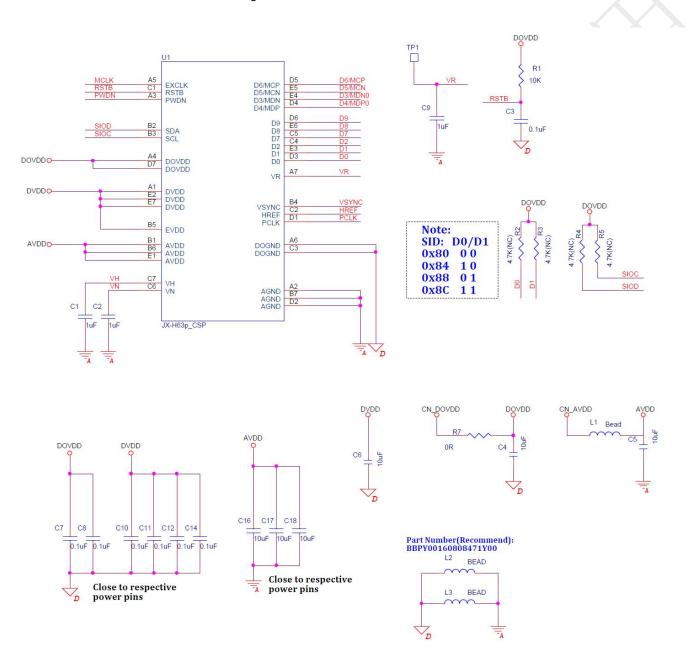
- 1, Maximum number of reflow cycles=3.
- 2, N2 gas reflow or control O2 gas ppm<500 as recommendation.



CSP Module Schematic (Reference):

Figure 17 shows reference schematics for CSP module.

Figure 17. Reference schematic for CSP module





Register Descriptions:

I2C Slave ID

The I2C slave ID is selectable by the initial state of pin D[0] and pin D[1].

Pin D[1]	Pin D[0]	Slave ID
		(Read/Write)
Х	Х	81/80
Х	Pull high	85/84
Pull high	Х	89/88
Pull high	Pull high	8D/8C

Sensor ID

Address (Hex)	Register Name	Default (Hex)	R/W	Description
0A	PIDH	08	R	PIDH[7:0]:Product ID MSBs.
ОВ	PIDL	48	R	PIDL[7:0]: Product ID LSBs.

System Control

Address (Hex)	Register Name	Default (Hex)	R/W	Description	
12	SYS	00	RW	System status set up SYS[7]: Soft reset initialize, "1": initial system reset, it will reset whole sensor to factory default status, and this bit will clear after reset. Default: "0": normal mode SYS[6]: Sleep mode on/off selection, "1": sensor into sleep mode. No data output and all internal operation stops. External controller can stop sensor clock, while I2C interface still can work. Default: "0": normal mode SYS[5]: mirror image on/off, "1": mirrored image output, "0": normal image output SYS[4]: flip image on/off, "1": flipped image output, "0": normal image output. SYS[3]: HDR mode on/off selection. "0": normal mode, "1": HDR mode. SYS[1]: vertical skip or full mode selection. "0": full mode,"1":vertical skip mode SYS[0]: Horizontal down sample mode enable.	
65	RAMP3	37	RW	RAMP3 [3:0]: Second stage black sun reference control. Strength: (Strong) 1,0,F,E,D,C,B,A,9,8,7,6,5,4,3,2. (Weak)	
69	PWC3	ВВ	RW	PWC3[3]: Second stage black sun switch on/off enable, "0": always off. "1": Black sun will switch to second stage when analog gain greater than 2x.	
6A	PWC4	1B	RW	PWC4[3:0]: first stage black sun control. Strength: (Strong) 1,0,F,E,D,C,B,A,9,8,7,6,5,4,3,2. (Weak)	
80	DigData	01	RW	DigData[7]: frame sync function enable DigData[6]: DVP data output sequence adjust	

AGC and AEC

Address (Hex)	Register Name	Default (Hex)	R/W	Description
------------------	------------------	------------------	-----	-------------



00	PGA	00	RW	Programmable gain, valid 00 to 3F, Total gain = 2^PGA[6:4]*(1+PGA[3:0]/16)	
01	EXP	1F	RW	Exposure line LSBs, EXP [7:0]	
02	EXP	00	RW	Exposure line MSBs, EXP[15:8].; Exposure time is defined by EXP[15:0] at line period base. T_{EXP} =EXP[15:0]* T_{Line}	

Black Level Control

Address (Hex)	Register Name	Default (Hex)	R/W	Description	
49	BLC_TGT	10	RW	Black level calibration target level. BLC_TGT[7]: sign bit."0" positive; "1" negative BLC_TGT[6:0]: target level.	
4A	BLCCtrl	05	RW	BLC control BLCCtrl[7]: BLC_B bit 10 BLCCtrl[6]: BLC_Gb bit 10 BLCCtrl[5]: BLC_Gr bit 10 BLCCtrl[4]: BLC_R bit 10 BLCCtrl[4]: BLC_R bit 10 BLCCtrl[1]: BLC action option. "0": Sensor do BLC only when triggered. "1": always do BLC. BLCCtrl[0]: auto BLC function on/off selection. "0": sensor stop calculate black value. "1": sensor calculates black value automatically.	
4B	BLC_B	00	RW	B channel black value LSBs. BLC_B[7:0]	
4C	BLC_Gb	00	RW	Gb channel black value LSBs. BLC_Gb[7:0]	
4D	BLC_Gr	00	RW	Gr channel black value LSBs. BLC_Gr[7:0]	
4E	BLC_R	00	RW	R channel black value LSBs. BLC_R[7:0]	
4F	BLC_H	00	RW	Black value MSBs. {BLC_R[9:8],BLC_Gr[9:8],BLC_Gb[9:8],BLC_B[9:8]}	

Frame Size and Window Control

Address (Hex)	Register Name	Default (Hex)	R/W	Description	
20	FrameW	6E	RW	Sensor frame time width LSBs; FrameW[7:0]	
21	FrameW	03	RW	Sensor frame time width MSBs; FrameW[15:8] FrameW[15:0]: sensor frame width	
22	FrameH	00	RW	Sensor frame time high LSBs ;FrameH[7:0]	
23	FrameH	03	RW	Sensor frame time high MSBs. FrameH[15:8] FrameH[15:0]: sensor frame high. Sensor frame rate is defined as Fpclk / (FrameW*FrameH). Fpclk: frequency of pixel clock.	
24	Hwin	80	RW	Image horizontal output window width LSBs: Hwin[7:0]	
25	Vwin	D0	RW	Image vertical output window high LSBs: Vwin[7:0]	



26	HVWin	22	RW	Image output window horizontal and vertical MSBs. { Vwin[11:8], Hwin[11:8]}	
27	HwinSt	6C	RW	Image horizontal output window start position LSBs. HwinSt[7:0]	
28	VwinSt	15	RW	Image vertical output window start position LSBs. VwinSt[7:0]	
29	HVWinSt	03	RW	Image output window horizontal and vertical start position MSBs. {VwinSt[11:8],HwinSt[11:8]}	

DVP Interface

Address (Hex)	Register Name	Default (Hex)	R/W	Description	
ос	DVP1	40	RW	DVP control 1. DVP1[6]: Sensor sun spot elimination control, "1": disable sun spot elimination, "0": enable sun spot elimination. DVP1[1:0]: DVP test mode output option. "00": DVP output normal image data. "01": DVP[9:0] = Output 10-bit walk "1" test pattern	
0D	DVP2	50	RW	DVP control 2. DVP2[3:2]: PAD drive capability. "00": min, "11": max.	
1D	DVP3	00	RW	DVP control 3 DVP3[7:0]: GPIO direction control for data output port D[7:0]. "1": enable output. "0": tri-state output.	
1E	DVP4	10	RW	DVP3[7:0]: GPIO direction control for data output port D[7:0]. "1": enable output. "0": tri-state output. DVP control 4 DVP4[7]: PCLK polarity control. "0": data output at rising edge of PCLK, "1":data output at falling edge of PCLK DVP4[6]: HREF polarity control. "0": positive, "1": negative DVP4[5]: VSYNC polarity control. "0": positive, "1": negative DVP4[4:0]: GPIO direction control for output port: PCLK, HREF, VSYNC and D[9:8] . "1": enable output. "0": tri-state output.	

MIPI Interface

Address (Hex)	Register Name	Default (Hex)	R/W	Description	
70	70 Mipi1 C9 RW Mipi timing control 1 Mipi1[7:5]: Tlpx Mipi1[4:2]: Tck-pre Mipi1[1]: Mipi 8/10 bit mode switch, "0": 10-bit, "1": 8-bit mode		Mipi1[7:5]: Tlpx Mipi1[4:2]: Tck-pre		
71	Mipi2	8A	RW	Mipi timing control 2 Mipi2[7:5]: Ths-zero Mipi2[4:0]: Tck-zero	
72	Mipi3	C8	RW	Mipi timing control 3 Mipi3[7:5]: Ths-prepare Mipi3[4:0]: Tck-post	
73	Mipi4 63 RW Mipi timing control 4 Mipi4[7]: Mipi pixel clock option Mipi4[6:4]: Ths-trail Mipi4[3:0]: Tck-trail		Mipi4[7]: Mipi pixel clock option Mipi4[6:4]: Ths-trail		
74	Mipi5	03	RW	Mipi timing control 5 Mipi5[1]: Mipi continues mode or strobe mode selection "1" free run; "0" Normal; Mipi5[0]: Mipi interface sleep on/off Mipi should wait a complete frame than enter sleep mode.	



				"1" Sleep mode enable; "0" Normal;	
75	Mipi6	2B	RW	Mipi data type ID;	
76	Mipi7	40	RW	Mipi word count LSBs	
77	Mipi8	06	RW	Mipi word count MSBs	

HDR

Address (Hex)	Register Name	Default (Hex)	R/W	Description
12	SYS	00	RW	SYS[3]: HDR mode on/off selection. "0": normal mode, "1": HDR mode.
05	SAEC0	1F	RW	Short exposure lines in HDR mode, SAEC[7:0]: LSB of short exposure lines in HDR mode, each bit equals to 1 lines.
06	SFramSt	1F	RW	Short exposure start position in HDR mode, [7:0]: each bit equals to 2 lines, short exposure packet start at SFramSt[7:0] *2 +3 lines relate to long exposure packet.
08	SAEC1	00	RW	SAEC1[0]: SAEC[8] MSB of short exposure lines in HDR mode, with Reg05

I2C Group Write

Address (Hex)	Register Name	Default (Hex)	R/W	Description
1F	GLat	00	RW	Group latch control Glat[7]: Group write trigger. "1": system will write reg0xC0 to 0xFF content to proper register. This bit will clear after group write. "0": inactive group write function.
C0	Group0	0A	RW	Group write 1 st data address
C1	Group1	0A	RW	Group write 1 st data value.
C2	Group2	0A	RW	Group write 2 nd data address
С3	Group3	0A	RW	Group write 2 nd data value.
				
FE	Group62	0A	RW	Group write 32 nd data address
FF	Group63	0A	RW	Group write 32 nd data value.



Document Revision Control

Version Number #	Date Released	Comments
R0.1	Sep 16,2021	Initial release of JX-H63P preliminary datasheet
R1.0	Dec 16,2021	Key spec info update
R1.1	Mar 13,2022	Key spec info update